Materials Declaration

Package	BGA
Body Size	23 X 23 mm
LeadCount	316
Option	SnAgCu
Ball Size	0.6 mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.6	6.59 E-01	343468
Resin	11.0	8.28 E-02	43155
Brominated compound	0.9	6.80 E-03	3544
Antimony	0.5	3.80 E-03	1981
Subtotal		7.52 E-01	392148

Laminate

Item	% of Laminate	Weight (g)	PPM
Laminate	46.1	3.81 E-01	198680
Cu	40.9	3.38 E-01	176321
Solder mask	7.7	6.37 E-02	33200
Nickel	1.8	1.50 E-02	7818
Brominated Compound	3.2	2.61 E-02	13603
Gold	0.4	3.00 E-03	1564
Subtotal		8.27 E-01	431185

Solder Ball

	% of Plating	Weight (g)	PPM
Sn	96.5	2.71 E-01	141244
Ag	3.0	8.40 E-03	4378
Cu	0.50	1.40 E-03	730
Subtotal		2.81 E-01	146352

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.00	1.43 E-02	7451
Pd	1.00	1.44 E-04	75
Subtotal		1.44 E-02	7526

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.86 E-02	20131

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Filler	77.0	3.90 E-03	2033
Resin	33.0	1.20 E-03	625
Subtotal		5.10 E-03	2658

Weight (g)	PPM
1.92 E+00	1000000

Mold Compound

Item	PPM	Method
Pb	Not Detected	EPA 3051/3052. ICP-OES.
Cd	Not Detected	EPA 3051/3052. ICP-OES.
Hg	2.90	EPA 3051/3052. ICP-OES.
Cr+6	Not Detected	EPA 3060A/7196A. UV-VIS.
PBB	Not Detected	EPA 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA 3540C/3550C. GC/MS.

Die Attach

Item	PPM	Method
Pb	Not Detected	EPA 3051/3052. ICP-OES.
Cd	Not Detected	EPA 3051/3052. ICP-OES.
Hg	Not Detected	EPA 3051/3052. ICP-OES.
Cr+6	Not Detected	EPA 3060A/7196A. UV-VIS.
PBB	Not Detected	EPA 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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